CENG 317 Progress report Jerreh Janneh n01093685

**Overall progress**

The TMP006 temperature sensors progress has been a little slow since delays due to multiple revisions of the PCB were made. As of week 11 the enclosure is due

**Financial status**

In terms of financial status, no additional money has been spent keeping me on budget thought some changes are necessary to factor in some parts I had not though of originally such as male/male extension jumpers and extra headers. This would increase the price of the budget by over $35 CAD

**Parts**

Available parts including the PCB, TMP006 temperature sensor and raspberry pi zero have been setup and soldered however a final test (for a screen capture to present later on) the board, because of all the revisions needs to be done more time will need to be taken to focus on the enclosure and any hardware issues that may arise

**Scheduling**

The progress made compare to the Gantt chart as seen on the sensors GitHub page does not align as again there have been delays, we are entering ID 12(Week 11) for the enclosure however the time originally allotted for milestones such as the PCB build and soldering is less than what time was taken. As a result, ID numbers 8-13 may need changing.

**Problems and opportunities**

As week 11 arrives I’m left with a lot less time however it’s still possible to have an enclosure created, tested, and completed my before presentations on week 12 by dedicating weekdays such as Tuesday and Wednesday to work on hardware and after I can take weekends to go though the budget and gnat chart to reflect what parts were needed and how long each milestone took. I use theses date as I need access to the prototype lab to make and changes like soldering. There will be a new id in the budget outlining the wires needed, cost, shipping and currency, whereas extending the time for the PCB solder, testing and breadboard build milestones